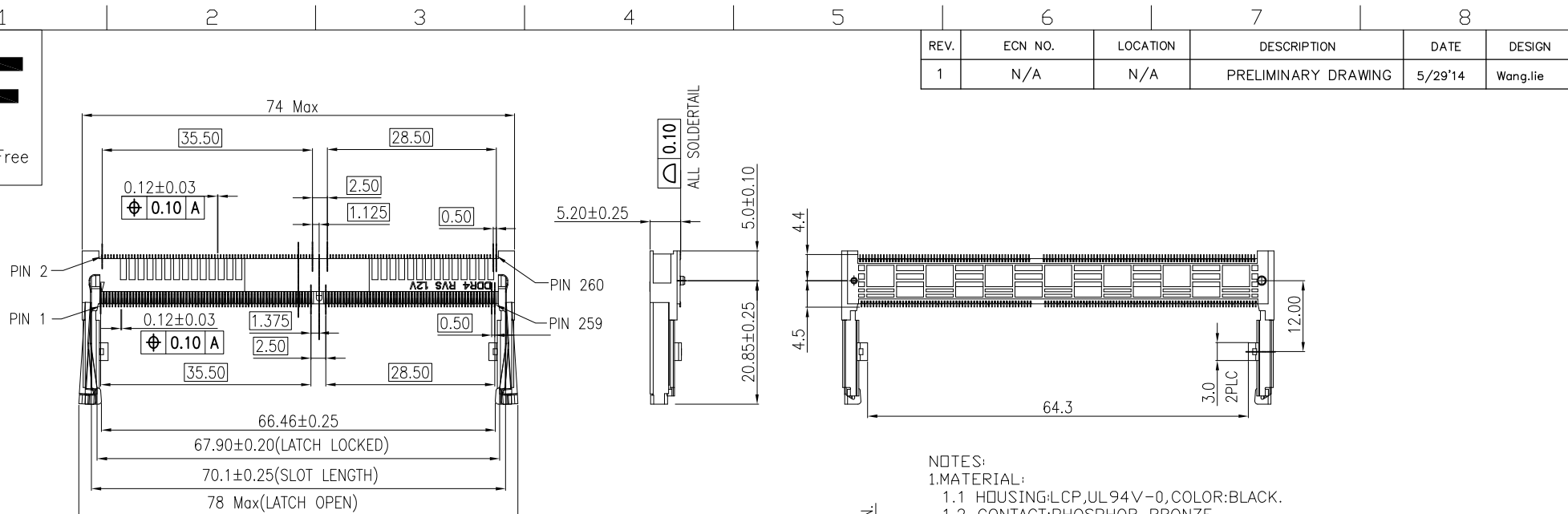


HF

Halogen Free



## NOTES:

## 1. MATERIAL:

1.1 HOUSING: LCP, UL94V-0, COLOR: BLACK.

1.2 CONTACT: PHOSPHOR BRONZE.

1.3 SOLDER PEG AND LATCH: STAINLESS STEEL.

## 2. FINISH:

2.1 CONTACT: 50u" MIN NICKEL UNDERPLATED ALL OVER.

GOLD FLASH PLATING ON SOLDER TAIL.

GOLD PLATING (THICKNESS SEE TABLE) ON CONTACT AREA.

2.2 SOLDER PEG:

50u" MIN NICKEL UNDERPLATED ALL OVER.

AU 2u" MAX ON SOLDER TAIL.

## 3. PART NUMBER DESCRIPTION:

40-42273-2600XRHF-L

HALOGEN CODE:

HF: HALOGEN FREE

R: TAPE &amp; REEL PACKING

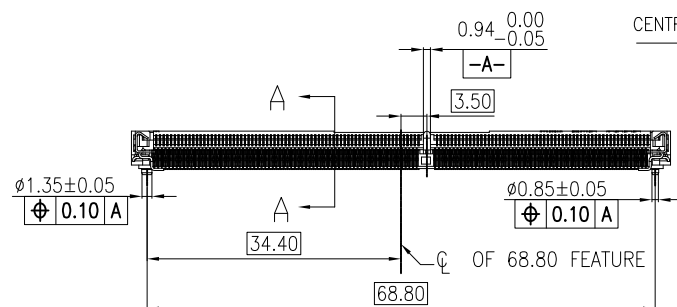
PLATING CODE:

1: GF 2: Au5u" 3: Au10u"

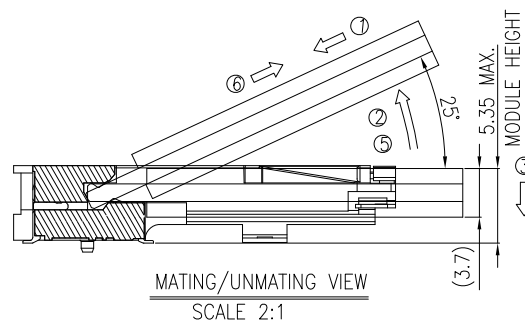
4: Au15u" 5: Au30u"

RESERVED

PIN NUMBER CODE: 260 PINS



CENTRE OF CARD SLOT

SECTION: A-A  
SCALE 2:1MATING/UNMATING VIEW  
SCALE 2:1

MATING: ① INSERTING (30°) → ② ROTATING → ③ FIXED

UNMATING: ④ UNFIXED → ⑤ ROTATING → ⑥ WITHDRAWING

TABLE 2

30u" Au	40-42273-26005RHF-L	x.	±0.30
15u" Au	40-42273-26004RHF-L	.x	±0.25
10u" Au	40-42273-26003RHF-L	.xx	±0.15
5u" Au	40-42273-26002RHF-L		
GF	40-42273-26001RHF-L		
PLATING THICKNESS	DEREN P/N		

DIM	TOL	DIM	TOL
x.	±0.30	x.	±2°
.x	±0.25	.x	±1°
.xx	±0.15		

DRAW NO.  
T-14-XXXX

REV. 1



CUSTOMER DRAWING	DATE	TITLE: DDR4 SODIMM 260P 5.2H RV5 (FOR LCFC) C-DWG
DESIGN: Wang.lie	5/29'14	P/N: SEE TABLE 2
CHECK: Bill.lin	5/29'14	SHEET: 1/3
APPROVAL: Bill.lin	5/29'14	SCALE: 1:1 UNIT: mm